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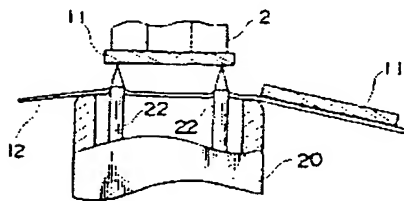
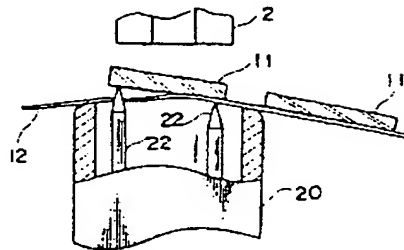
APPLICATION DATE : 03-04-86
APPLICATION NUMBER : 61075494

APPLICANT : MITSUBISHI ELECTRIC CORP;

INVENTOR : NAKAMURA ATSUTOSHI;

INT.CL. : H01L 21/68

TITLE : APPARATUS FOR REMOVING CHIP



ABSTRACT : PURPOSE: To enable a chip to be peeled off from a sheet while preventing dislocation of other chips located therearound, by operating an ejector pin for pushing up one side of the chip and an ejector pin for pushing up the other side of the chip at different timing from each other.

CONSTITUTION: A wafer chip 11 is transported to below a suction collet 2. A push-up section 20 is moved toward and contacted with an expand sheet 12 so that the expand sheet 12 is sucked. One of ejector pins 22 or the left-side pin as viewed on the drawings is elevated so as to pass through the expand sheet 12 and raise up the wafer chip 11 obliquely, whereby a space is defined between the wafer chip 11 and the expander sheet 12. Then, upon elevation of the other ejector pin 22, the suction collet 2 is lowered to suck the wafer chip 11.

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